

# Characterization of Integrated Optical Strain Sensors Based on Silicon Waveguides

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**Abstract**—Microscale strain gauges are widely used in micro electro-mechanical systems (MEMS) to measure strains such as those induced by force, acceleration, pressure or sound. We propose all-optical strain sensors based on micro-ring resonators to be integrated with MEMS. We characterized the strain-induced shift of the resonances of such devices. Depending on the width of the waveguide and the orientation of the silicon crystal, the linear wavelength shift per applied strain varies between 0.5 and 0.75 pm/microstrain for infrared light around 1550 nm wavelength. The influence of the increasing ring circumference is about three times larger than the influence of the change in waveguide effective index, and the two effects oppose each other. The strong dispersion in 220 nm high silicon sub-wavelength waveguides accounts for a decrease in sensitivity of a factor 2.2 to 1.4 for waveguide widths of 310 nm to 860 nm. These figures and insights are necessary for the design of strain sensors based on silicon waveguides.

**Index Terms**—Optical sensors, strain measurement, silicon-on-insulator, integrated optics, optical waveguide, microsensors, mechanical sensors.

## I. INTRODUCTION

MICROSCALE strain gauges are widely used in micro electro-mechanical systems (MEMS) to measure strains such as those induced by force, acceleration, pressure or (ultra)sound [1], [2]. These sensors are traditionally based on a piezoresistive or piezoelectric material which transduces the strain to an electrical signal. Alternatively, optical resonators can be used as sensing element, providing particular benefits:

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high-speed readout, small sensor size, small multiplexer size (1 mm<sup>2</sup>), insensitivity to electromagnetic interference, and no danger of igniting gas explosions with electric sparks.

Integrated optics technology allows the optical strain sensors, as well as their multiplexing circuit, to be integrated with MEMS. The sensing elements and their multiplexers can often be fabricated in a single processing step. Silicon-on-insulator (SOI) has emerged as one of the focus platforms for integrated optics, and is relatively straightforward to integrate with MEMS, as MEMS are most commonly made of silicon. Micro-electronic research institutes have tailored CMOS fabrication processes to the demands of SOI optical circuits, and now offer cheap and reproducible wafer-scale fabrication [3], [4]. The high refractive index contrast of SOI ridge waveguides allows for a small device footprint, and single-mode guides have a cross section of only 400 nm × 220 nm.

We employ ring resonators as sensing element. Such a resonator consists of a waveguide which is looped, forming a closed cavity which has specific optical resonance wavelengths. Any change in the size or in the refractive index of this waveguide shifts its resonances, and this shift can be accurately recorded.

Several groups have reported on sensor micro opto-electro-mechanical systems (MOEMS) that are based on silicon integrated optical ring resonators, such as strain gauges [5], [6], or pressure sensors [7]–[9]. An application of particular interest is as ultrasound sensor for medical intravascular ultrasonography (IVUS). IVUS has been recommended for the diagnostics of atherosclerosis [10], [11]. IVUS is an invasive technique for blood vessel imaging where the sensor is attached to a catheter and brought inside the artery. Using an array of sensors improves the image quality but wiring many piezoelectric sensors with coaxial cables requires too much space for this application. As solution, we proposed a micro-machined ultrasound transducer with optical readout [12]. This sensor consists of a silicon ring resonator integrated in a membrane that deforms due to ultrasonic waves. Integrated optical multiplexers allow high-speed read-out of many sensors via one optical fiber and, moreover, insensitivity to electromagnetic interference allows usage inside MRI scanners.

The relation between strain and silicon waveguides is of broader interest than sensing. Electro-mechanical modulation of silicon optical resonators may be employed to modulate optical signals, for application in the field of telecommunication [13]. As alternative to silicon waveguide-based ring resonators, it is also possible to use photonic crystals cavities, which have their own dispersion relations [14]. Strain has also been used to modify the birefringence of larger SOI rib waveguides [15].

Strain is inevitable when using silicon photonic circuits on a flexible substrate [16]. Another interesting field of research is the strain-induced change in the electronic band-gap and the optical refractive index of silicon, with the possibility to introduce second-order nonlinearity [17]–[19]. However, details of the relation between an applied strain and the shift in optical resonance of ring resonators have not been studied.

We characterized the shift of the resonance wavelengths which is caused by a well-defined strain. This includes a characterization of the change in the effective index of the sub-wavelength silicon waveguide. We studied the influence of the waveguide width and the influence of the orientation of the silicon crystal. This knowledge is required for the design of mechanical sensors based on silicon integrated optics, such as ring resonators or Mach–Zehnder interferometers. Also, we quantified the contribution of three physical effects: the strain-induced change in circumference of the resonator, the strain-induced change in effective index of the waveguide, and the dispersion which is strong in sub-wavelength silicon waveguides.

This paper is organized as follows: first we present the devices which are used to study the effect of strain on silicon optical waveguides (see Section II), then we derive opto-mechanical theory describing these devices (see Section III), after which we detail the experimental setup and methodology (see Section IV). The characterization and the analysis of the devices are presented in Sections V and VI, respectively, and we conclude in Section VII.

## II. DEVICES

In this section, we first describe the SOI-technology in which the devices are fabricated, secondly detail the ring resonators and then describe the sets of devices that we studied.

The integrated optical devices are in silicon-on-insulator technology, with 220 nm thick waveguides of mono-crystalline silicon. The guides are on top of a 2  $\mu\text{m}$  thick buried oxide (BOX) layer which is on top of a 675  $\mu\text{m}$  thick silicon substrate. We deposited a 2  $\mu\text{m}$  thick  $\text{SiO}_2$  cladding layer using plasma-enhanced chemical vapor deposition (PEVCD), so that the silicon waveguides are embedded in silica. The devices were fabricated via the EU-funded ePIXfab consortium at IMEC (Leuven, Belgium) [3], [4]. IMEC fabricated the devices in their CMOS line with 193 nm deep-UV lithography. The waveguides are not exactly rectangular but have a side-wall-angle of  $10^\circ$ . We measured the average widths of the fabricated waveguides with a helium ion microscope (Carl Zeiss SMT), providing an accuracy of 15 nm.

We designed long racetrack-shaped ring resonators in an “add-drop” configuration (see Fig. 1), and excite the “input” waveguide with infrared light with wavelengths  $\lambda$  around a center wavelength  $\lambda_c$  of 1550 nm. A directional coupler couples light from the “input/output” waveguide to the resonator, and an identical coupler is used half-way the racetrack to couple light to a “drop” waveguide. The transmitted spectrum  $T(\lambda)$  in the “output” port has dips at the resonance wavelengths of the resonator. We characterized the couplers and 59% of the power is coupled from the waveguide to the track, such that

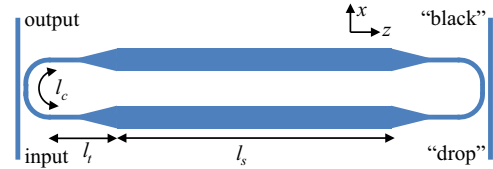


Fig. 1. Sketch of racetrack resonator with in/output ports (not to scale). Long straight waveguide has length  $l_s = 1000 \mu\text{m}$  and width  $w$ . Taper section has length  $l_t = 64.35 \mu\text{m}$  (4.35  $\mu\text{m}$  long waveguide of width 400 nm, taper with a length varying from 0 to 60  $\mu\text{m}$ , followed by a waveguide of width  $w$  to close the space.) Coupler section has length  $l_c$  and consists of two 10  $\mu\text{m}$  long parallel guides (width  $\sim 400$  nm, gap 220 nm), and bends with a radius of 5  $\mu\text{m}$ .

the power which goes straight through the coupler  $|t|^2 = 41\%$ . Having a strong coupling in a symmetric add-drop configuration gives resonance dips with good extinction ratio even for high losses in the racetrack or for variations in coupling (e.g., due to fabrication) [20].

Silicon is anisotropic, so its deformation depends on the direction in which a force is applied. Therefore two sets of devices were fabricated and characterized; one with the long side of the racetrack parallel to the  $\langle 110 \rangle$  direction of the silicon crystal and one with the long side parallel to the  $\langle 100 \rangle$  direction of the silicon crystal. Reference [21] explains the crystal planes in a “(100) wafer” as we used. We characterized the influence of the width of the waveguide on the shift in resonance, therefore each set of devices consists of resonators with waveguide widths varying from 310 nm up to 860 nm.

## III. THEORY

This section presents the theory of ring resonators such as presented in the previous section, i.e., a looped waveguide with a varying width. First, Section III-A presents the optical theory of ring resonators, then Section III-B derives the opto-mechanical theory. Section III-C applies the theory to the long racetrack resonators under study. The relations derived in this section are used as fitting function of the measured spectra, and as basis for the analysis of the measurements.

### A. Ring and Racetrack Resonators

The transmitted optical power  $T$  of a micro-ring resonator with two lossless couplers in an add-drop configuration such as shown in Fig. 1 is [20]

$$T = \frac{\alpha^2 |t|^2 + |t|^2 - 2\alpha |t|^2 \cos(\delta)}{1 + \alpha^2 |t|^4 - 2\alpha |t|^2 \cos(\delta)} \quad (1)$$

where  $|t|^2$  is the straight-through power of the coupler and  $\alpha^2$  is the power transmission due to one round-trip through the ring ( $\alpha = 1$  means zero loss).  $T$  thus describes the optical power transmitted from the input to the output of the connecting waveguide, and is wavelength dependent because  $\delta$  is wavelength-dependent. The phase delay  $\delta$  of one round-trip through the ring (including passing the couplers) is

$$\delta = \oint n_e(\rho, \lambda) \frac{2\pi}{\lambda} d\rho = \langle n_e(\lambda) \rangle \frac{2\pi}{\lambda} l \quad (2)$$

where the waveguide effective index  $n_e(\rho, \lambda)$  is averaged over the position  $\rho$  in the track with circumference  $l$  as  $\langle n_e(\lambda) \rangle \equiv \frac{1}{l} \oint n_e(\rho, \lambda) d\rho$ . The effective index in the coupler is approximated equal to the effective index of a single isolated waveguide. The strong modal dispersion in sub-wavelength silicon waveguides is approximated to be linear around the center wavelength  $\lambda_c$ , and is expressed in terms of the effective group index  $n_g \equiv n_e - \lambda \frac{\partial n_e}{\partial \lambda}$ , so

$$n_e(\rho, \lambda) = n_e(\rho) + (n_e(\rho) - n_g(\rho)) \left( \frac{\lambda}{\lambda_c} - 1 \right) \quad (3)$$

where  $n_e$  and  $n_g$  at the right-hand side, denoted without  $\lambda$  dependence, are evaluated at  $\lambda_c$ . As  $\lambda$  and  $\rho$  are independent

$$\langle n_e(\lambda) \rangle = \langle n_e \rangle + (\langle n_e \rangle - \langle n_g \rangle) \left( \frac{\lambda}{\lambda_c} - 1 \right) \quad (4)$$

from which it is observed that the transmission spectrum of a racetrack resonator with varying width is described by the same relation as a resonator with a single waveguide, but with averaged effective index  $\langle n_e \rangle$  and group index  $\langle n_g \rangle$ .

Equation (1) with (2) and (4) will be fitted to the measured resonance spectra to accurately obtain  $\langle n_g \rangle$  and  $\langle n_e \rangle$ , from which the resonance wavelengths are calculated.

### B. Strain-Induced Resonance Shift of Ring Resonators

This section details the shift in the resonances of a ring resonator due to an applied mechanical strain. Four physical effects play a role when elongating a ring- or racetrack resonator. First, the circumference of the track  $l$  increases. Second, the cross section of the waveguide shrinks due to the Poisson effect. Third, the refractive indices of the silicon and SiO<sub>2</sub> change due to the photo-elastic effect. The latter two effects together influence the effective index  $n_e$  of the waveguide. Fourth, the shift in resonance is affected by the dispersion in the waveguide.

In our case, a homogeneous strain  $S_z$  is applied parallel to the long sides of the racetrack resonator (the  $z$ -direction). The transmitted spectrum of the connecting waveguide shows dips at the resonance wavelengths  $\lambda_m$  when  $\delta = m2\pi$ , or

$$m\lambda_m = \oint n_e(\rho, \lambda_m, S_z) (1 + S_\rho(\rho, S_z)) d\rho. \quad (5)$$

The effective index of the waveguide depends on a mechanical deformation. The local strain in the direction of the track  $S_\rho$  is taken into account by stretching each element  $d\rho$  to  $(1 + S_\rho)d\rho$ . For the straight waveguide of the racetracks as in Fig. 1, the  $z$ - and  $\rho$ -directions coincide, whereas they do not for the coupler section. We found that the relation between an applied strain  $S_z$  and the shift in resonance wavelength is linear, which is explained by the fact that the applied strains are small. A description of this linear influence can be found by taking the first derivative of (5) with respect to  $S_z$ ,

$$m \frac{\partial \lambda_m}{\partial S_z} = \oint \left\{ \left( \frac{\partial n_e}{\partial S_z} + \frac{\partial n_e}{\partial \lambda_m} \frac{\partial \lambda_m}{\partial S_z} \right) (1 + S_\rho) + n_e \frac{\partial S_\rho}{\partial S_z} \right\} d\rho$$

which we evaluate at zero strain (i.e.,  $S_z = S_\rho = 0$ ). Solving this equation for  $\partial \lambda_m / \partial S_z$ , substituting  $m$  from (5), and dividing

by track circumference  $l$  gives

$$\frac{\partial \lambda_m}{\partial S_z} = \frac{\lambda_c}{\langle n_g \rangle l} \oint \left( \frac{\partial n_e}{\partial S_z} + n_e \frac{\partial S_\rho}{\partial S_z} \right) d\rho \quad (6)$$

with  $\lambda_c$  the resonance wavelength  $\lambda_m$  without deformation. This equation is easiest understood when considering a resonator with a single waveguide shape (i.e.,  $\langle n_e \rangle = n_e$  and  $\langle n_g \rangle = n_g$ ). In that case,

$$\frac{\partial \lambda_m}{\partial S_z} = \underbrace{\frac{n_e}{n_g}}_{\text{dispersion}} \left\langle \underbrace{\frac{\lambda_c}{n_e} \frac{\partial n_e}{\partial S_z}}_{\text{eff. index}} + \underbrace{\lambda_c \frac{\partial S_\rho}{\partial S_z}}_{\text{track-length}} \right\rangle \quad (7)$$

where the influence of the different physical effects are indicated. Without dispersion,  $n_e/n_g = 1$ . For the part of the track which is in the direction of the applied strain  $S_\rho = S_z$ , so  $\partial S_\rho / \partial S_z = 1$ , hence the contribution of the track-length change is simply  $\lambda_c$ .

### C. Strain-Induced Resonance Shift of Long Racetracks

We measured very long racetracks because this will allow for neglecting the influence of the tapers and the couplers. In the long racetrack resonators, Equation (5) reads

$$m\lambda_m = 2l_s n_s (1 + S_z) + \int_{\text{tapers}} n_e (1 + S_\rho) d\rho + \int_{\text{couplers}} n_e (1 + S_\rho) d\rho \quad (8)$$

where the contributions of the different sections of the track are separated (see Fig. 1, with  $l_s$ ,  $l_t$ , and  $l_c$  indicating the straight, taper, and coupler sections, respectively) and  $n_s$  is the effective index of the long straight waveguide. We calculate the first-order influence of strain on this racetrack similarly to (6), and rewrite the equation such that the influence of the tapers and the couplers is written as a correction to the shift caused by the long straight guides

$$\begin{aligned} \langle n_g \rangle \frac{\partial \lambda_m}{\partial S_z} &= \lambda_c \left( \frac{\partial n_s}{\partial S_z} + n_s \right) \\ &+ \frac{\lambda_c}{l} \int_{\text{tapers}} \left( \frac{\partial n_e}{\partial S_z} + n_e \frac{\partial S_\rho}{\partial S_z} - \frac{\partial n_s}{\partial S_z} - n_s \right) d\rho \\ &+ \frac{\lambda_c}{l} \int_{\text{couplers}} \left( \frac{\partial n_e}{\partial S_z} + n_e \frac{\partial S_\rho}{\partial S_z} - \frac{\partial n_s}{\partial S_z} - n_s \right) d\rho. \end{aligned} \quad (9)$$

We will justify later that the second and third term of the right-hand side of this equation are small compared to the first one, and hence can be neglected, resulting in

$$\langle n_g \rangle \frac{\partial \lambda_m}{\partial S_z} \approx \lambda_c \left( \frac{\partial n_s}{\partial S_z} + n_s \right). \quad (10)$$

The taper is a waveguide in the  $z$ -direction with a width varying from 400 nm up to the width  $w$  of the long section waveguide. The second term at the right-hand side of (9) is the relative contribution of the taper to the resonance shift, with respect to the contribution of a waveguide with width  $w$  of the same



length. The relative contribution of the taper is smaller than the relative contribution of a 400 nm wide waveguide of the same length. Using (10), it is thus found that the second term of the right-hand side of (9) is smaller than

$$\frac{4l_t}{l} \left| \underbrace{\langle n_g \rangle \frac{\partial \lambda_m}{\partial S_z}}_{\text{width under study}} - \underbrace{\langle n_g \rangle \frac{\partial \lambda_m}{\partial S_z}}_{\text{width 400 nm}} \right|. \quad (11)$$

The third term of (9) comes from the effect of the couplers including the bend waveguides. This contribution can be either positive (as for the long waveguides) or negative (as the path-length might shrink due to the Poisson effect). We expect the magnitude to be smaller than twice the effect of a straight waveguide of equal length that is strained in its long direction. Thus the third term in (9) is smaller in magnitude than

$$2 \frac{2l_c}{l} \left( \langle n_g \rangle \frac{\partial \lambda_m}{\partial S_z} \right). \quad (12)$$

As will be shown in Section V, the maximum measured difference in  $\langle n_g \rangle (\partial \lambda_m / \partial S_z)$  for the devices under study with different waveguide widths is 10%. For these long racetracks,  $4l_t/l = 11\%$ , so the second term in (9) is smaller than 1.1%. The third term is smaller than  $4l_c/l = 5\%$ . Equation (10) is used in the characterization of the measurements. We characterized both  $\langle n_g \rangle$  and  $\partial \lambda_m / \partial S_z$ . The effective index of the straight waveguide  $n_s$  is computed with a numerical mode solver, which allows us to extract the strain-induced change in effective index.

Similar to (7) in the more general Section III-B, we indicate the effects of the different phenomena in (10)

$$\frac{\partial \lambda_m}{\partial S_z} = \underbrace{\frac{n_s}{\langle n_g \rangle}}_{\text{dispersion}} \left( \underbrace{\left( \frac{\lambda_c}{n_s} \frac{\partial n_s}{\partial S_z} + \lambda_c \right)}_{\text{eff. index track-length}} \right). \quad (13)$$

This result is used in the interpretation of the measurements in Section VI. In fact, track-averaged group index  $\langle n_g \rangle$  can be approximated as the group index  $n_g$  of the straight waveguide. We have used the numerical mode solver to show that this approximation is valid within 1%. In our analysis, we use the track-averaged group index which was accurately measured.

#### IV. METHODOLOGY

We characterized the photonic chips in an automated setup in which they are bent such that the top layer with the racetrack resonators is strained. Transmission spectra of the resonators were recorded for elongations varying from 0 to 275 microstrain. As example, Fig. 2(a) shows a resonance dip of the measured spectra for increasing strain. The resonance wavelengths, and the group index  $n_g$ , were extracted from fitting a relation for ring resonator transmission. Fig. 2(b) shows the resonance wavelength  $\lambda_m$  plotted versus the applied strain.

##### A. Mechanical Setup: Four Point Bending

We designed and fabricated a mechanical setup in which the chips are bent such that the top layer with the photonic circuit is uniformly strained (see Fig. 3). The setup is equipped with elastic elements to provide an accurate bending moment to the

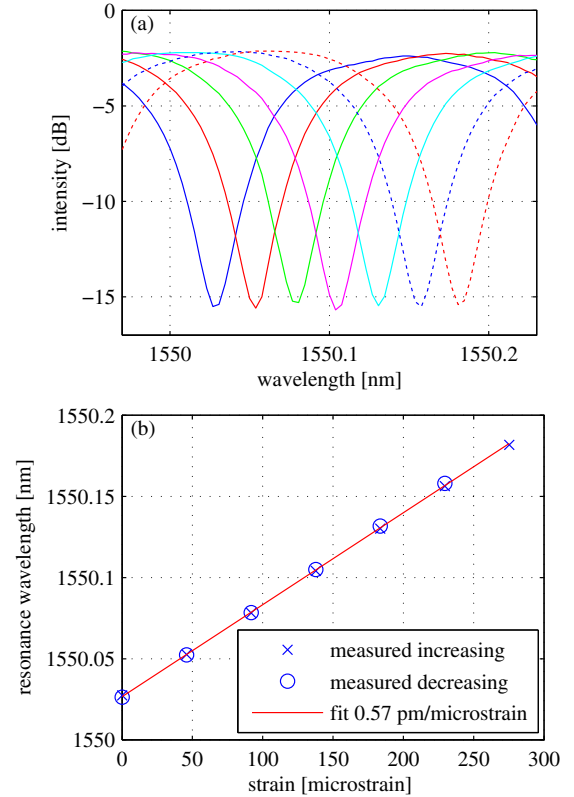


Fig. 2. Example of resonance shift due to an applied strain. (a) Small span of 7 measured spectra for increasing values of applied strain. Resonance dips shift to the red. Racetrack in the  $\langle 100 \rangle$  crystalline direction, with waveguide width 400 nm. (b) The wavelengths of the resonance dips  $\lambda_m$  in (a) is plotted versus the applied strain  $S_z$ . The wavelengths of the resonance dips for decreasing values of strain are also plotted. Resonance shift  $\partial \lambda_m / \partial S_z$  is obtained from a linear fit.

chip, without hysteresis or other non-linearities. Between the two inner supports, the chip experiences a constant bending moment  $M$  (known as *pure bending*) [22]

$$M = \frac{a_1(a_4 - a_3)}{4a_2} L \quad (14)$$

with  $L$  the load applied at the lever. The bending of the chip is described by plate bending theory for *thin plates with small deflections* [23], as its thickness  $H$  is small compared to its width  $W$  and length. An assumption in this theory is that the normal stresses in the  $x$ -direction can be neglected, so that there is no strain  $S_x$  in the  $x$ -direction and the width  $W$  of the chip does not change due to the applied load. In the setup, the deflection of the chip at considerable distance from its ends can be assumed to be cylindrical. In this mechanical analysis the influence of upper layers of the chip (BOX layer, waveguide layer, and cladding layer) is neglected as their total thickness of  $4.220 \mu\text{m}$  is much smaller than the chip thickness of  $675 \mu\text{m}$ . Hooke's law and plate bending theory give the relation between the stress  $\sigma_z$  and strain  $S_z$  in the chip [21], [23]:

$$\sigma_z = \frac{E_z}{1 - \nu_{xz}\nu_{zx}} S_z \quad (15)$$

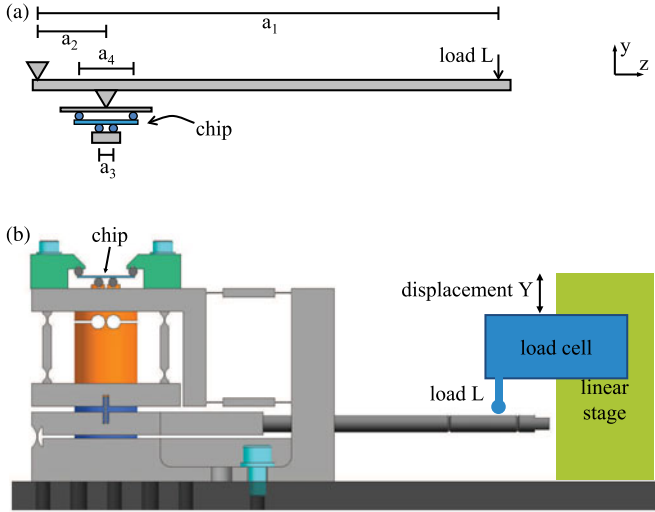


Fig. 3. (a) Analysis of the mechanical setup. (b) Sketch of the mechanical setup. Composed of the CAD drawing that was used to fabricate the setup (left-hand side), and a sketch of the linear stage with the load cell.

with Young's modulus<sup>1</sup>  $E_z$  and anisotropic Poisson's ratios<sup>2</sup>  $\nu_{xz}$  and  $\nu_{zx}$ . Combining (14) and (15) with the cylindrical deflection of the chip gives the strain  $S_z$  on the top surface of the chip in the mechanical setup

$$S_z = \frac{3a_1(a_4 - a_3)(1 - \nu_{xz}\nu_{zx})}{2a_2WH^2E_z}L. \quad (16)$$

A precise linear stage (Newport MFA-CC) applies a force to the lever, while a load cell (Omega LECB5) measures the actual applied load  $L$ . It was observed that the relation between the displacement of the linear stage  $Y$  and the applied load  $L$  is linear in the regime of our measurements, and also that the repeatability of the linear stage position  $Y$  was higher than the repeatability of the load cell. Therefore, we extracted a single number for the resistance of the chip to bending,  $\partial Y/\partial L$ , from all the measurements performed on a chip.

### B. Optical Setup

The transmission spectra of the racetracks were measured with near infrared light around  $\lambda_c = 1550$  nm. An amplified spontaneous emission light-source (OptoLink C-band ASE) was used to emit this light, and a 5 nm span of the spectra were recorded with an optical spectrum analyzer (OSA) (Yokogawa AQ6370B). The input and output waveguides of the racetrack resonators are routed to out-of-plane grating couplers at convenient locations on the chip, and coupled to cleaved optical fibers via free-space [24], [25]. These fibers were mounted on stages with piezo positioning, and automatically actively aligned in the horizontal ( $x,z$ )-plane before recording a spectrum. All transmission spectra are normalized to the transmission spectrum of a reference waveguide, which was smoothed by convolution

with a 1 nm wide Gaussian window to remove Fabry-Pérot resonances originating from reflections of the out-of-plane grating couplers.

A relation for ring resonator transmittance, Equations (1)–(4), was fitted to the recorded spectrum. The ring length  $l$  and straight-through power of the coupler  $|t|^2 = 41\%$  were fixed, while the effective index  $\langle n_e \rangle$ , group index  $\langle n_g \rangle$ , resonator waveguide loss  $\alpha^2$  and fiber-coupling loss were fitted. The resolution bandwidth of the OSA was incorporated in this fitting by convoluting the calculated spectrum with a 20 pm wide Gaussian curve. For the zero-strain measurement, the mode number  $m$  of the resonance closest to  $\lambda_c$  was estimated from (5) where the effective index  $n_e(\rho, \lambda_c, 0)$  was calculated using a mode solver (film mode matching method in FimmWave by PhotonDesign [26]). This dip was followed over consecutive measurements. An accurate initial guess of  $\langle n_e \rangle$  and  $\langle n_g \rangle$  (thus the wavelengths of the resonance dips) is necessary for the Levenberg-Marquardt fitting algorithm [27]. Therefore, the resonance dips were first found using *findpeaks* [28] and from this  $\langle n_e \rangle$  and  $\langle n_g \rangle$  were estimated via (5). This initial estimate allows for automated fitting of the spectra. With this fitting, the free parameters in (1)–(4) could be obtained, and  $\lambda_m$  was calculated from (5) with an accuracy much higher than the resolution bandwidth of the OSA.

### C. Measurements

We characterized chips with the racetracks in the  $\langle 110 \rangle$  crystalline direction and with the racetracks in the  $\langle 100 \rangle$  direction. The measurements were repeated several times. First, the chip was manually placed in the setup. Then resonators with different widths of the straight waveguide were automatically measured. The strain of the racetrack was increased and decreased from 0 to approximately 275 microstrain, with 6 steps in each direction [see Fig. 2(a)]. The transmittance spectrum was recorded for each applied strain, and the resonance position  $\lambda_m$  that started closest to  $\lambda_c$  was extracted. The effective group index  $\langle n_g \rangle$  was also extracted from this spectrum. For each value of applied strain, the measured load  $L$  and the position of the linear stage  $Y$  were recorded. Per measurement set of increasing and decreasing strain, the resonance shift per displacement of the load cell,  $\partial\lambda_m/\partial Y$ , was obtained from a linear fit, and so was the relation between the displacement and the applied load,  $\partial Y/\partial L$ . We observed that both relations were indeed linear in this regime. The strain-induced resonance shift is then

$$\frac{\partial\lambda_m}{\partial S_z} = \frac{\partial\lambda_m}{\partial Y} \cdot \frac{\partial Y}{\partial L} \cdot \frac{\partial L}{\partial S_z} \quad (17)$$

in which the first two terms on the right-hand side are measured and the last term is calculated from (16).

The relation between the displacement of the load cell and the measured load can be interpreted as the resistance of the chip and setup to bending. The average value for the chip with the racetracks in the  $\langle 110 \rangle$  direction is  $\partial Y/\partial L = 0.128 \mu\text{m/mN}$  and the average value for the chip with the racetracks in the  $\langle 100 \rangle$  direction  $\partial Y/\partial L = 0.135 \mu\text{m/mN}$ .

<sup>1</sup> $E_i$  is the Young's modulus along axis  $i$ .

<sup>2</sup> $\nu_{ij}$  is the Poisson's ratio that corresponds to a contraction in direction  $j$  when an extension is applied in direction  $i$ .

#### D. Numerical Mode Solver

For the analysis of the measurements, we calculated the effective index at zero strain,  $n_e(\rho, \lambda_c, 0)$  using the film mode matching method in FimmWave [26]. Also the effective group index  $n_g(\rho)$  at  $\lambda_c$  was calculated using this mode solver. The track-averaged effective index  $\langle n_e \rangle$  and group index  $\langle n_g \rangle$  are then straightforward to calculate.

#### E. Measurement Uncertainty Analysis

The uncertainty in the measurements was estimated following the guidelines of [29]. The relative errors of the three terms on the right-hand side of (17) are added quadratically, as they are independent. The chips with the racetrack resonators in the  $\langle 110 \rangle$  and  $\langle 100 \rangle$  directions were placed in the mechanical setup and measured 6 and 5 times, respectively.

1)  $\partial\lambda_m/\partial Y$ : The value for  $\partial\lambda_m/\partial Y$  is averaged over the repetitive measurements, and the uncertainty is estimated as the standard deviation. The relative uncertainty did not significantly depend on the width of the waveguide, and the maximum relative uncertainty (of all widths) is used. The uncertainty for the chips with the waveguides in the  $\langle 110 \rangle$  and  $\langle 100 \rangle$  directions are 3.1% and 1.1%, respectively. The measurement-to-measurement difference mainly originated from repositioning the chip in the setup, which was done before each measurement. Repeating a measurement without repositioning the chip in the setup gives a measurement-to-measurement difference which is negligible. We could not attribute this difference to a slight tilt of the chip with respect to the setup (around the  $y$ -direction). We do not fully understand why the uncertainty in the  $\langle 110 \rangle$  direction is higher, but the strong angle dependency of Poisson's ratio around the  $\langle 110 \rangle$  direction may play a role. Also, we had to reassemble the setup between various  $\langle 110 \rangle$  measurements, while the measurements of the  $\langle 100 \rangle$  chip were performed consecutively in a mainly empty laboratory.

2)  $\partial Y/\partial L$ : The value of  $\partial Y/\partial L$  did not significantly depend on the position of the chip in the setup. All measurements (for different widths of the waveguide, and repetitions of the measurements) are averaged to obtain  $\partial Y/\partial L$ . The statistical uncertainty (arising from random fluctuations) is estimated as the standard deviation, and the systematic uncertainty of the system (load cell, load cell voltage source, and A/D converter) is estimated as 3%. The standard deviation of the 30 measurements in the  $\langle 110 \rangle$  direction is 2.8%, and the standard deviation of the 45 measurements in the  $\langle 100 \rangle$  direction is 0.7%. This difference can be explained by the fact that we increased the integration time of the read-out of the load cell from 50 samples at 1 kHz for the  $\langle 100 \rangle$  direction measurements to 1000 samples at 1 kHz for the  $\langle 110 \rangle$  direction measurements. The output voltage of the load cell is a few mV, which required this longer integration time of our A/D converter (National Instruments USB-6251 DAQ). The uncertainties of  $\partial Y/\partial L$  are thus 5.8% and 3.7% for the chips with the racetracks in the  $\langle 110 \rangle$  and  $\langle 100 \rangle$  directions, respectively.

3)  $\partial L/\partial S_z$ : The mechanics of the setup is described by (16). The material properties, dimensions, and uncertainties that are used in this equation are listed in Table I. The uncertainty

TABLE I  
MATERIAL PROPERTIES, DIMENSIONS, AND ESTIMATED  
UNCERTAINTIES OF MECHANICAL SETUP

Quantity	Value	Uncertainty	
$E_z/(1 - \nu_{xz}\nu_{zx}), \langle 110 \rangle$	170 GPa <sup>a</sup>	4 GPa	2.5% <sup>b</sup>
$E_z/(1 - \nu_{xz}\nu_{zx}), \langle 100 \rangle$	141 GPa <sup>a</sup>	4 GPa	2.5% <sup>b</sup>
$a_1$	156 mm	0.3 mm	0.2% <sup>c</sup>
$a_2$	24 mm	0.03 mm	0.1% <sup>d</sup>
$a_3$	5 mm	0.03 mm	0.6% <sup>d</sup>
$a_4$	20 mm	0.03 mm	0.1% <sup>d</sup>
Chip $W$	24 mm	0.3 mm	1.2% <sup>c</sup>
Chip $H$	0.675 mm	0.01 mm	1.7% <sup>e</sup>
$\partial L/\partial S_z, \langle 110 \rangle$	12.7 mN/ $\mu$ strain	0.6 mN/ $\mu$ strain	4.7%
$\partial L/\partial S_z, \langle 100 \rangle$	10.5 mN/ $\mu$ strain	0.5 mN/ $\mu$ strain	4.7%

<sup>a</sup> From [21].

<sup>b</sup> Estimated.

<sup>c</sup> Measured with digital electronic calipers, maximum error 0.5 mm.

<sup>d</sup> Estimated fabrication uncertainty, maximum error 0.05 mm.

<sup>e</sup> Measured with digital electronic calipers, maximum error 0.02 mm.

$\sigma$  of a quantity whose uncertainty is estimated as a maximum deviation  $u$  is given by  $\sigma = u/\sqrt{3}$  [29]. In the computation of the uncertainty of  $\partial L/\partial S_z$ , we have treated all uncertainties as independent and approximated the influence of all the uncertainties as linear.

4) *Group Index*  $\langle n_g \rangle$ : We found that the track-averaged effective group index does not depend on the applied strain. Therefore all measurements of a device are averaged, and the uncertainty is estimated as the standard deviation. These were 78 and 65 measurements for the racetracks in the  $\langle 110 \rangle$  and  $\langle 100 \rangle$  directions, respectively. The relative uncertainty did not depend much on the width of the straight waveguide in the racetrack nor on the crystalline orientation, so that we have used the maximum of 0.03%.

5) *Effective Index*  $\langle n_e \rangle$ : In the analysis of the measurements, we calculated the effective index with a numerical mode solver. We do not know the uncertainty, as it is mostly related to the difference between the simulated waveguide and the fabricated waveguide. Therefore, we estimated the uncertainty in the effective index as the difference between the measured effective group index  $\langle n_g \rangle$  and the track-averaged group index as calculated with the same mode solver (see Fig. 5).

## V. CHARACTERIZATION

We characterized two chips with long racetrack resonators; one chip with the resonators in the  $\langle 110 \rangle$  silicon crystalline direction and one with the resonators in the  $\langle 100 \rangle$  direction. A strain  $S_z$  was applied to the top surface of the chips, where the resonators are placed. The strain was increased to approximately 275 microstrain, and then decreased to zero strain in steps of approximately 45 microstrain. Per applied strain, the transmission spectrum of the resonator was recorded, as is shown in Fig. 2(a). The wavelength of the resonance dip which started closest to 1550 nm is extracted from each of the spectra, and plotted versus the applied strain in Fig. 2(b). The shift per applied strain  $\partial\lambda_m/\partial S_z$  is obtained from a linear fit. This is done for racetracks with different widths, and the resonance shifts per strain are presented in Fig. 4. It can be seen that the racetracks

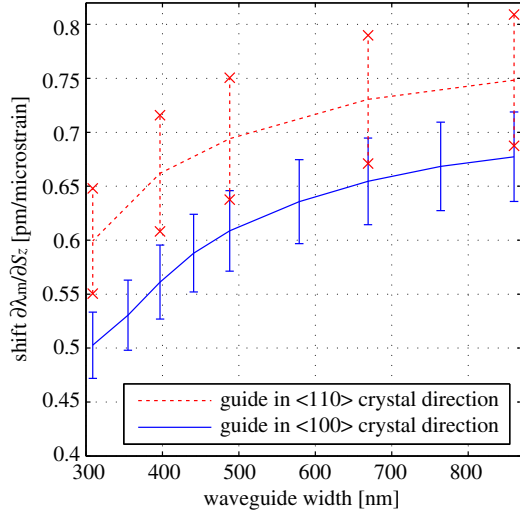


Fig. 4. Measured resonance shift per applied strain  $\partial\lambda_m/\partial S_z$ , with resonance wavelength  $\lambda_m$  and strain  $S_z$ .

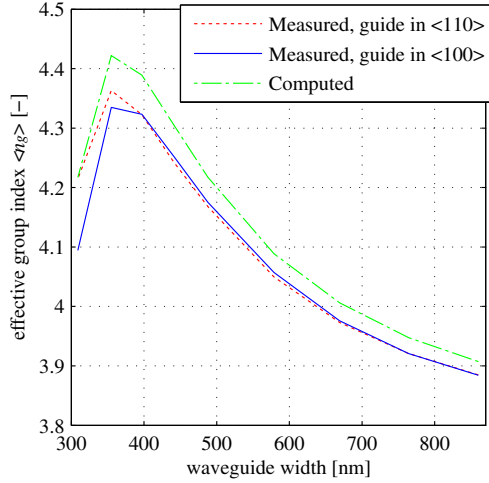


Fig. 5. Measured and calculated track-averaged effective group indices  $\langle n_g \rangle$ . Measured for racetracks in the  $\langle 100 \rangle$  and in the  $\langle 110 \rangle$  silicon crystalline directions.

in the  $\langle 110 \rangle$  direction are slightly more sensitive than the tracks in the  $\langle 100 \rangle$  direction, and that the resonators with wider waveguides are more sensitive to strain than the ones with narrower waveguides widths. The latter can be attributed to the dispersion in the waveguide, as shown in Section VI. The estimated uncertainties are with respect to the absolute value of  $\lambda_m/S_z$ , and a large part of the uncertainty is a systematic bias and equal for all measurements. Considering only the statistical (or random) uncertainties, we found that the racetracks in the  $\langle 110 \rangle$  and  $\langle 100 \rangle$  directions have a significantly different shift in resonance.

The track-averaged effective group indices  $\langle n_g \rangle$  were also extracted from the spectra and are presented in Fig. 5. We also calculated the effective group index with the numerical mode solver. The calculated and measured track-averaged effective group indices agree within 3%.

The change in effective index due to strain,  $\partial n_e/\partial S_z$ , is calculated using (10). We measured the resonance shift  $\partial\lambda_m/\partial S_z$

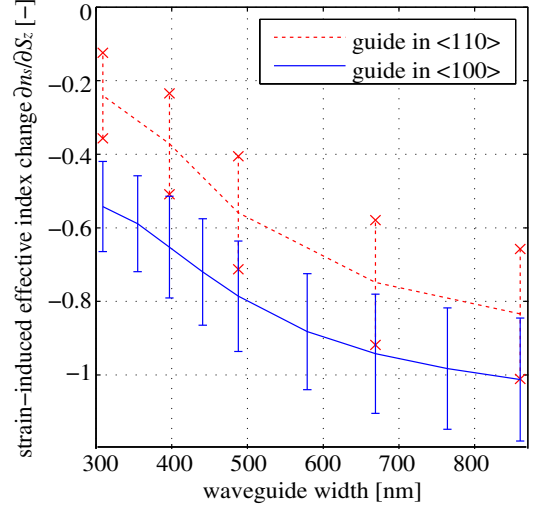


Fig. 6. Change in effective index of a straight waveguide,  $n_s$ , due to a strain,  $S_z$ , applied in the direction of the guide.

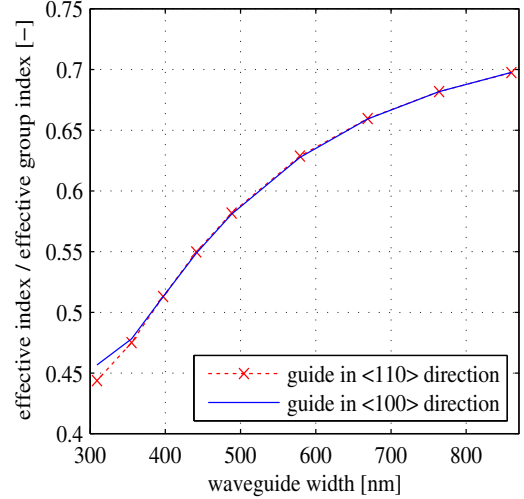


Fig. 7. Influence of dispersion on the strain-induced resonance shift,  $n_s/\langle n_g \rangle$ . Effective index  $n_s$  calculated with the mode solver. Track-averaged effective group index  $\langle n_g \rangle$  is measured.

and the effective group index  $\langle n_g \rangle$ , and we calculated the effective index  $n_s$  of the straight waveguide with the numerical mode solver. The resulting  $\partial n_s/\partial S_z$  is shown in Fig. 6.

## VI. ANALYSIS

In this section, we interpret the measured shift and indicate the contributions of different physical effects: the elongation of the track, the change in effective index and the dispersion of the waveguide. Equation (13) shows how these effects shift the resonance wavelength. The effect of the elongation of the track ( $\lambda_c$ ) and the effect of the change in effective index are added. The change in effective index  $\partial n_s/\partial S_z$  is negative, so the two effects oppose each other. The dispersion of the waveguide,  $n_s/\langle n_g \rangle$ , is smaller than unity, and thus damps the shift. Fig. 7 presents  $n_s/\langle n_g \rangle$ , in which it can be seen that this damping is stronger for small waveguides. Fig. 8 presents the resonance wavelength



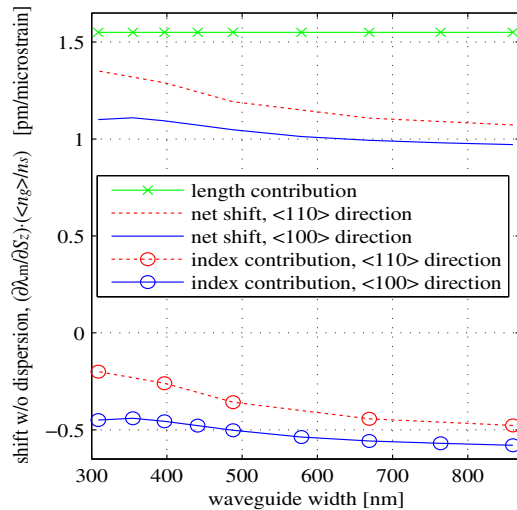


Fig. 8. The hypothetical strain-induced shift in resonance in which the dispersion is excluded. The two different contributions to this shift (track-length change and effective-index change) are shown. Results for the racetracks in the  $\langle 110 \rangle$  and the  $\langle 100 \rangle$  directions are shown.

shift with dispersion excluded. The shift due to the change in the effective index increases (in magnitude) with increasing width of the guide. The higher resonance shift for wider waveguides  $\partial\lambda_m/\partial S_z$  is thus due to the dispersion, and not due to the change in effective index of the waveguide.

## VII. CONCLUSION

We measured the strain-induced shift of the resonances of optical racetrack resonators in silicon-on-insulator technology. For waveguides with a width of 400 nm, the resonance wavelength shift per applied strain is 0.55 pm/microstrain when the racetrack is parallel to the  $\langle 100 \rangle$ -direction of the silicon crystal, and 0.66 pm/microstrain when the racetrack is parallel to the  $\langle 110 \rangle$ -direction. We observed largest sensitivity for wider waveguides; a racetrack with 860 nm wide waveguides oriented in the  $\langle 110 \rangle$ -direction has a resonance shift of 0.75 pm/microstrain. We have studied elongations up to 275 microstrain, and observed a linear relation between the resonance wavelength and the applied strain.

The effect of the strain-induced increase in track circumference and the effect of the strain-induced change in waveguide effective index oppose each other. The effect of the strain-induced increase in circumference is about three times larger than the effect of the change in effective index. The strong dispersion in the sub-wavelength silicon waveguides lowers the change in wavelength shift approximately by a factor two. In fact, the lower dispersion of the wider waveguides is the reason that these devices are more sensitive.

This paper addressed how micro-ring resonators transduce an applied strain into a shift of their optical resonance wavelengths. Sensor MEMS or MOEMS consist, next to the transducer, also of a mechanical structure that acts on the transducer and an interrogation system that reads the transducer. A variety of interrogation concepts exist for monitoring the shift in the resonances of optical resonators [30]–[36]. The detection limit of MOEMS

sensors depends on the designs of the mechanical structure and the interrogation system. These designs are application specific as they depend, for example, on the bandwidth of the measured signal (e.g., [12] presents the design of an ultrasound sensor).

In this work, we have characterized a novel type of optical strain sensors which can be integrated in micro-electro-mechanical systems (MEMS). We believe these sensors open opportunities in different fields of applications such as in the medical, petrochemical, or oil&gas markets, by offering specific advantages such as high-speed readout over kilometer distances, integrated optical multiplexing, and small device size. Moreover, by removing the need for galvanic connections, susceptibility to electromagnetic disturbance is eliminated.

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